

# INTAMSYS<sup>®</sup> PC

INTAMSYS<sup>®</sup> PC is an advanced PolyCarbonate based filament designed specifically for FDM/FFF 3D printing. In addition to high printing quality, great mechanical strength and heat resistance, INTAMSYS<sup>®</sup> PC offers excellent impact strength and fracture toughness, making it the ideal choice for engineering applications.

PHYSICAL PROPERTIES	TEST METHOD	UNITS	TYPICAL VALUE
Density	ISO 1183	g/cm <sup>3</sup>	1.18-1.20
Glass transition temperature	DSC, 10°C /min	°C	113
Softening temperature of filament	Custom method	°C	127 - 130
Melt index	300°C, 1.2 kg	g/10min	23 - 26
Moisture content	Thermogravimetric	%	≤0.1
Odor	-	-	Almost odorless
Solubility	-	-	Insoluble in water

MECHANICAL PROPERTIES <sup>1</sup>	TEST METHOD	UNITS	TYPICAL VALUE
Tensile strength	ISO 527	MPa	60.7
Young's modulus	ISO 527	MPa	2480
Elongation at break	ISO 527	%	5.6
Bending strength	ISO 178	MPa	84.3
Bending modulus	ISO 178	MPa	1685
Impact strength	ISO 179	kJ/m <sup>2</sup>	15.6

Note:

1. All testing specimens were printed using a FUNMAT HT under the following conditions: Printing temperature = 255 °C, printing speed = 45 mm/s, number of shells = 2, and 100% infill.

## Disclaimer

The typical values presented in this document are intended for reference and comparison purposes only. They should not be used for design specifications or quality control purposes. Actual values may vary significantly with printing conditions. End-use performance of printed parts properties can be impacted by, but not limited to, part design, environmental conditions, printing conditions, etc. Product specifications are subject to change without notice.

Each user is responsible for determining the safety, lawfulness, technical suitability, and disposal/recycling practices of INTAMSYS materials for the intended application. INTAMSYS makes no warranty of any kind, unless announced separately, to the fitness for any particular use or application. INTAMSYS shall not be made liable for any damage, injury or loss induced from the use of INTAMSYS materials in any particular application.